

Chokes for Data and Signal Lines

Material Data Sheet

Product Class: Date		SMD Double Choke R4 B82793*0***N2** 14.10.2011					Ebre	6 B8275 C474 5 9412	N			
IMDS ID												
if available												
Version: 07												
Product Part (IMDS: semi component)	Material Class (IMDS: Material)		Material (Classification) VDA 231	Substance			TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)		
Active Part	for L ≤ 100 μH		Ceramic	4B	Nickel Zinc Ferrite			100	12645-50-0	30.0		
	f1 > 41	00	Ceramic	4B	Manganese Zin	c Ferr	te	100	12645-49-7	29.7		
	for L > 100 μH		Duromer	2C	Parylene			100	25722-33-2	0.3		
	Heavy M	letal		1C	Cu			100	7440-50-8	11.4		
	Elastomer			2B	Polyurethane (PUR)			100	68400-67-9	0.6		
Encapsulation and Mounting	Thermoplastic Elastomer			2A	Liquid Crystal Polymer (LCP)			70	147310-94-9	42.0		
				ZA	Glass fiber			30	65997-17-3			
				2B	Polydimethylsiloxane (PDMS) others *)			98 2	63148-62-9	5.0		
	Heavy Metal			1C	Sn			100	7440-31-5	0.2		
Termination	Heavy Metal			1C	Cu			94	7440-50-8	10.6		
			1C	Sn			6	7440-31-5	10.0			
	Heavy Metal			1C	Ni			100	7440-02-0		Х	
	Heavy Metal			1C	Sn			100	7440-31-5	0.2		
	•			•	•				Sum in total:	100.0		
Size W x L x H [max. in mm] 6.0 x 9.4 x 4.8 Not part of a pro	Wei [approx 0.2 oduct clas	x. in g] 25		Numbers 3*0***N2**								
Contact [Dr. Johann Reindl, MAG EPQM					Important remarks:						
Division T	DK Electr	onics AG, Magnetics Business Group (MAG)				1)						
Address F	Rosenheimer Strasse 116b, 81669 Munich						product parts, substance otherwise regulated	es etc. that ar	e below a percentage	e of 0.1 % by we	eight, if not	
				hann.reindl@tdk-elec		2)	This Material Data Shee herein. We expressly po	oint out that al	I values and stateme	nts contained he	erein are	
*) others: .(not de				ces acc. GADSI	_)		based on our best prese or binding product speci ELECTRONICS AG AN REPRESENTATION OF STATUTORY, WITH RE HEREIN, INCLUDING E WARRANTY OF MERC	ifications, unle D ITS AFFILI R WARRANT EGARD TO T BUT NOT LIM	ess otherwise explicit ATES HEREBY EXP Y, WHETHER EXPR HE STATEMENTS A ITED TO ANY REPF	ly agreed in writ RESSLY DISCL ESS, IMPLIED (ND VALUES CO ESENTATION (ing. TDK AIM ANY DR DNTAINED DR	
							oducts are compatible with striction of the use of certain	the requirem	ents according to Art	. 4 (substance r	estrictions)	
	ions for th	ne Prod	luct Class / F	Product accord	ing to Annex III:	(☑ va	alid 🗆 not valid)					
✓ no exemptions;												

□ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

 \square Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;

☐ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

□ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

□ Exemption 7 (c)-1: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

□ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;

☐ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

□ Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

☐ Other Exemption than above